



Università degli Studi di Padova

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Stray light from dust in Virgo

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Stray light problem

- Stray light injects additional noise into the ITF: currently visible as bumps and peaks at low f
- Need to develop mitigation strategies by finding the main scatterers & quantify the stray light power
- Tapping/shaking tests help find mechanical resonances
- Stray light simulations can provide estimates of the fraction of stray light that couples back into the ITF & its main sources





Stray light sources

Main sources:

- Surface roughness
- Dust contamination

Optics have extremely low roughness -> dust can be the leading contributor to stray light in Virgo

Surface roughness



Scattering due to non-perfectly smooth surfaces

Dust contamination



Dust scattering is described by **Mie Theory:**

- Particles are considered spherical & dielectric
- Their surface distribution function *f(D)* is modeled
- Particles produce both forward and back scatter components

distribution particles ust

Dust particle distribution *f(D)* in clean environments is usually modeled via IEST CC21246D:

$$f(S, \mathrm{CL}, D) = -\frac{d}{dD}N_p(S, \mathrm{CL}, D)$$

$$N_p(S, \mathrm{CL}, D) = 10^{|S| \left[\log_{10}^2(\mathrm{CL}) - \log_{10}^2(D) \right]}$$

 N_p is the **number of particles**/0.1m² with diameter $\geq D$

S is the particle distribution **slope** (S = -0.926 in IEST, experimental data not very much in agreement)

CL is the **cleanliness** level of the surface: in IEST it's equivalent to the maximum particle size/0.1m² (x-intercept)



- - CL = 200 - - CL = 400 - CL = 600

VIR-0511A-21



If modeled with IEST CC21246D the CL is calculated as:

 $\log_{10} \text{CL} = \left[1.08 \left(\log_{10} h + \log_{10} \rho + \log_{10} t + 0.773 \log_{10} X_{c} - 1.248\right)\right]^{1/2}$





Dust contamination monitoring campaign

MOTIVATION & PURPOSE

- Have reasonable cleanliness (CL) estimates
- Produce realistic estimates of stray light from dust

GOALS

- Monitor level of cleanliness of optics in different environments and over time
- Highlight critical situations and adopt mitigation strategies

 Expose clean silicon wafers next to optics in representative locations (first in the squeezing environment SQZ)

METHOD

 Take pictures of exposed wafers to extract particle size distribution









Dust images

CAMERA SYSTEM	IMAGES ACQUISITION	IMAGES PROCESSING	
 Images of wafers taken via camera system in ISO 3 Clean Room Camera with resolution ~5 µm is mounted over an illuminating LED ring Wafers' area of 2.8x1.8 cm is imaged Correspondence pixel-µm is determined 	 Optimal values for numerical aperture and height of illuminating LED ring were set Multiple identical images for noise-averaging purposes are taken Images are acquired via PixeLINK Image Capture (freeware) 	 ImageJ: images are combined as projection of image stacks LIGO MATLAB code to count particles and determine diameters (set the luminosity threshold, below which pixels are considered background and discarded) 	
	Single image	Particle Size Distribution Threshold Comparison	









Position	Camera aperture	-Slope	CL
SDB2	5.6	0.45 ± 0.02	1429 ± 170
SDB2	8	0.39 ± 0.03	1702 ± 320
EDB	5.6	0.53 ± 0.02	881 ± 60
EDB	8	0.48 ± 0.02	998 ± 110
SQZVertical	5.6	0.38 ± 0.05	1312 ± 410
SQZVertical	8	0.42 ± 0.04	918 ± 200
WS1	5.6	0.34 ± 0.02	1642 ± 300
WS1	8	0.28 ± 0.03	2678 ± 800

Fits results are displayed in the table

- Wafers placed horizontally except SQZVertical (placed vertically)
- Wafers exposed for a month except WS1 (exposed for a week)

Comment & Conclusions

- Fit results are **similar** in spite of wafers' variety of placement locations
- Overall: CL higher than standard values considered in initial analyses
- Saturation effect visible at small diameters in the data distributions (especially for smaller apertures) due to camera resolution
- Fit **not** in agreement with IEST model: other theoretical particle distribution include Gaussian and uniform
- **SQZVertical** and **WS1** are not cleaner than the others, as one would expect (possible handling process "spoiled" the wafers in a similar way?)

Analyses of O3 wafers

First we analyzed wafers placed in the SQZ environment employed during the third observation run O3 MOLYBDENUM MORPHOLOGY

TITANIUM POWDER ON A CLEAN WAFER

Images acquisition: fine tuning

Calibrated metal-based powder (Molybdenum & Titanium)

Use calibrated powder to determine **best** correct camera system **parameters** by taking pictures with different:

- Exposure time
- Camera aperture
- Focus

Extract particle counts via MATLAB code: For each image, code will output particle size distribution as a function of luminosity threshold



Determine best values of parameters: Analyze distributions and find the ones more **similar** to the known one



Dust scattering simulations



Simulations of stray light from dust are performed via FRED Optical Software Engineering (<u>https://photonengr.com/</u>):

Particle distributions from wafers' images will be the **input** values for the simulations

Wafer -> particle distribution -> scattering model to apply to nearby optics









Dust scattering simulations
Bust souttering sinialations

Mirror	Integrating Sphere TIS [ppm]	Dust Analyses TIS [ppm]
M4	258(4)	169
M5	241(12)	228



Conclusions

PRELIMINARY STUDIES

- Dust is projected to be a **major** source of scattering in SQZ
- Dust distribution on optics difficult to model, better **measure** it

DUST IMAGES WITH CAMERA SYSTEM

- We have identified a procedure for determining surface particulate contamination in a cleanroom environment
- Preliminary studies on O3 wafers: found **CL** values are much higher than standard values (which are up to CL = 1000)
- Preliminary studies on O3 wafers: experimental data distributions not in agreement with IEST STD CC1246D: this could suggest a need for more data, shortcomings in IEST's ability to represent our environment, or handling contamination
- Dust images with **calibrated** distribution of powder can aid setting right parameters for imaging system and will allow to increase the accuracy of measured distributions



Future work

DUST IMAGES WITH CAMERA SYSTEM

- Analyze dust images of samples placed in SQZ environment during O4 Commissioning
- Setup numerical **simulations** of stray light from dust, once reliable particle distributions are derived
- Investigate other particle distributions available in FRED to fit the data

CALIBRATION WITH SAMPLED DUST

- Analyze images from different areas of wafers
- Study the criticality of **focus**
- Use other calibrated parameters like 10 & 90 **percentiles** to help differentiate between curves
- Calculate integrals of curves to determine total #particles
- Develop a strategy to discern between **threshold** values and determine the right one
- Explore other types of combinations in **ImageJ** (e.g. use sum rather than minimum intensity projections)

Additional slides

Surface cleanliness level CL

In order to see how much the BSDF is affected by the choice of the CL, we plotted the BSDF as a function of CL for a fixed value of the particle distribution slope *S*

By taking the ratio between the BSDF for each CL value and the BSDF for CL = 200, a scale factor can be derived:

- CL = 400: scale factor = 23
- CL = 600: scale factor = 174
- CL = 800: scale factor = 787



Mie scatter BSDF (S = -0.926)



Wafers in O3 (SQZ environment)

- WS1: on ESQB, one week exposure
- SQZVertical: on ESQB, vertical
- SDB2: on top of threshold of tower structure, behind detection bench minitower
- EDB: on on top of external detection bench (EDB)





LIGO MATLAB code



- Lower thresholds tends to overestimate the number of particles (by counting background pixels as real particles) and their diameter
- Higher thresholds tends to underestimate the number of particles and their diameter
- · A compromize is needed to be found

Wafers in O3 (SQZ environment)



M4 & M5 particle distributions

		Particle Dis	stribution 20	201007		
4.5 -					+	fit dM412.mat
3.5 -				•		
3.0 -						
2.5 -						
^{2.0} - Slope =	0.38					
0	1	2 3	s ala Diamatar	4 D ((m))	5	6
		Log ⁻ (Fallin		<i>D</i> , μm)		
4.5 -				201007	+	fit dM512.ma
4.0 -	-		lifter -			
3.5 -		17		la Salir		
20-					r	
3.0						Ţ
2.5 -						
│	0.46					
^{2.0} Slope =	0.46					L

Mirror	Slope	CL	
M4	0.378 ± 0.008	2786 ± 143	
M5	0.460 ± 0.008	1703 ± 69	